M. Yasuda, et al. USSN: 10/040,804

Page 2

that such a petition has been inadvertently overlooked and is required. As provided below, charge Deposit Account **04-1105** for any required fee.

Please make the following changes:

IN THE CLAIMS

1. (Twice Amended) An electronic component including a plurality of electrodes deployed on a same plane surface and connected to another electronic component and connection materials placed on said electrodes,

said connection materials placed on said electrodes including

a composite connection material formed of a core and a conductor covering said core, said core having a low modulus of elasticity at room temperature smaller than a modulus of elasticity of said conductor at room temperature, and

a single-layer connection material formed of a conductor alone, wherein said composite connection material and said single-layer connection material selectively occupy said electrodes, respectively.

2. (Amended) The electronic component according to claim 1, wherein said composite connection material is placed on an electrode among electrodes arranged in an electrode region of said electronic component, said electrode being located in an area where a relatively greater stress is likely to be exerted repeatedly than a stress exerted on another area of the electrode region due to heat generated during operation of said electronic component, and said single-layer connection material is placed on an electrode in said another area.

Marked-up versions or the amended claims are provided in an annex to this responnse.